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(12) **United States Design Patent** (10) **Patent No.:** **US D911,987 S**  
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(54) **SEMICONDUCTOR ELEMENT**

6/4257; G02B 6/4261; G02B 6/4262;  
G02B 6/428; G02B 6/4281

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See application file for complete search history.

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(73) Assignee: **TAMURA CORPORATION**, Tokyo  
(JP)

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(\*\*) Term: **15 Years**

(Continued)

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*Primary Examiner* — Elizabeth J Oswecki

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(74) *Attorney, Agent, or Firm* — JCIPRNET

(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
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361/679.01, 713, 728, 736, 760, 761, 772,  
361/775, 783, 820; 174/250, 253;  
438/15, 25, 26, 51, 55, 63, 64, 106  
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;  
H01L 21/4814; H01L 21/4846; H01L  
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H01L 23/13; H01L 23/14; H01L 23/147;  
H01L 2924/171; H01L 2924/1711; H01L  
2924/1715; H01L 2924/17151; H01L  
2924/181; H01L 2924/1811; H01L  
2924/1815; H01L 2924/19042; H01L  
2924/1905; H01L 23/58; H01L  
2224/08054; H05K 1/026; H05K 1/14;  
H05K 1/141; H05K 1/142; H05K 1/144;  
H05K 1/18; H05K 1/181; H05K 1/182;  
H05B 41/14; G02B 6/4256; G02B

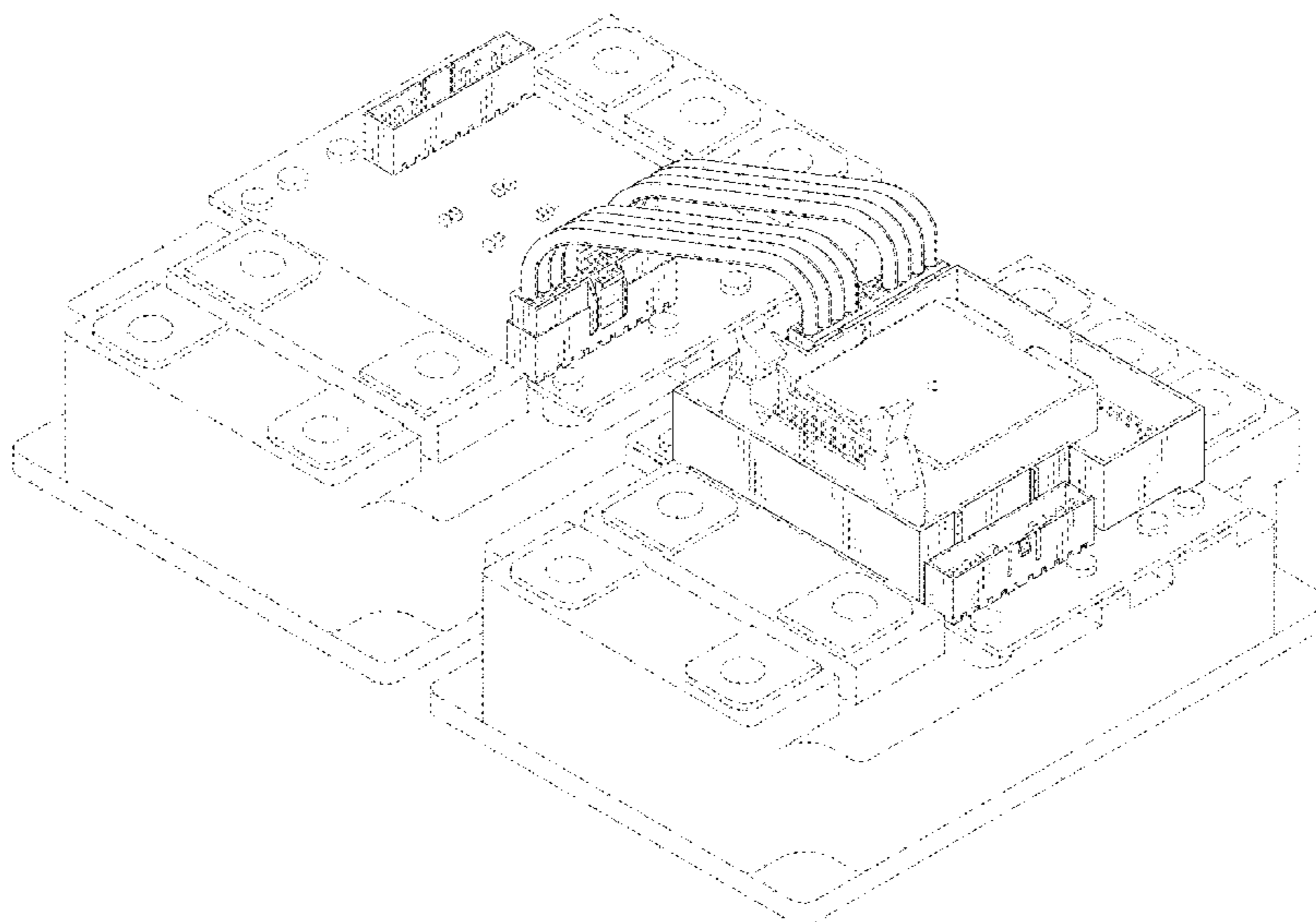
(57) **CLAIM**

The ornamental design for a semiconductor element, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a semiconductor element showing our new design;  
FIG. 2 is a front view of the semiconductor element of FIG. 1;  
FIG. 3 is a rear view of the semiconductor element of FIG. 1;  
FIG. 4 is a left side view of the semiconductor element of FIG. 1;  
FIG. 5 is a right side view of the semiconductor element of FIG. 1;  
FIG. 6 is a top view of the semiconductor element of FIG. 1; and,  
FIG. 7 is a bottom view of the semiconductor element of FIG. 1.  
The broken line portions of the semiconductor element in FIGS. 1-7 form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



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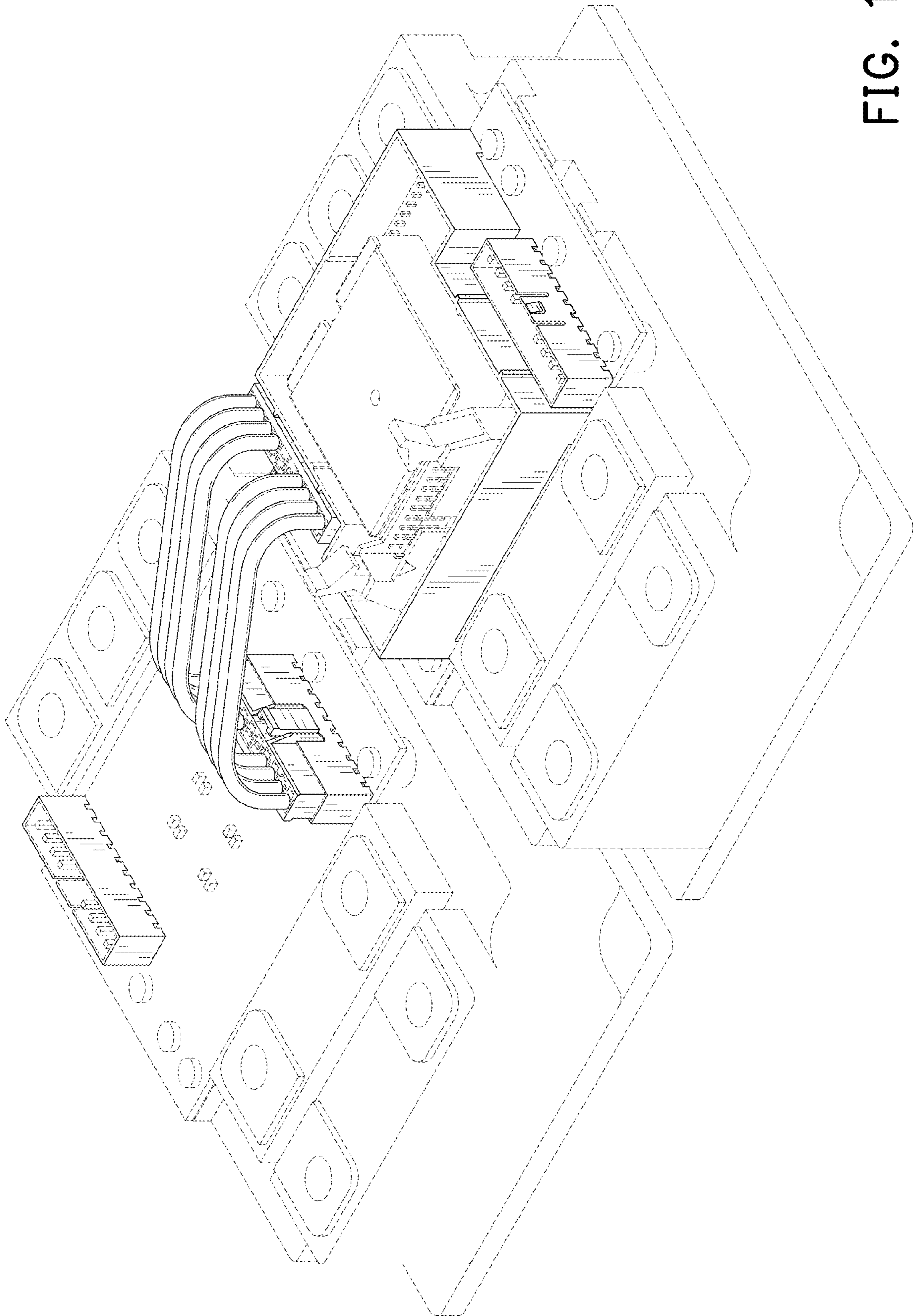


FIG. 1

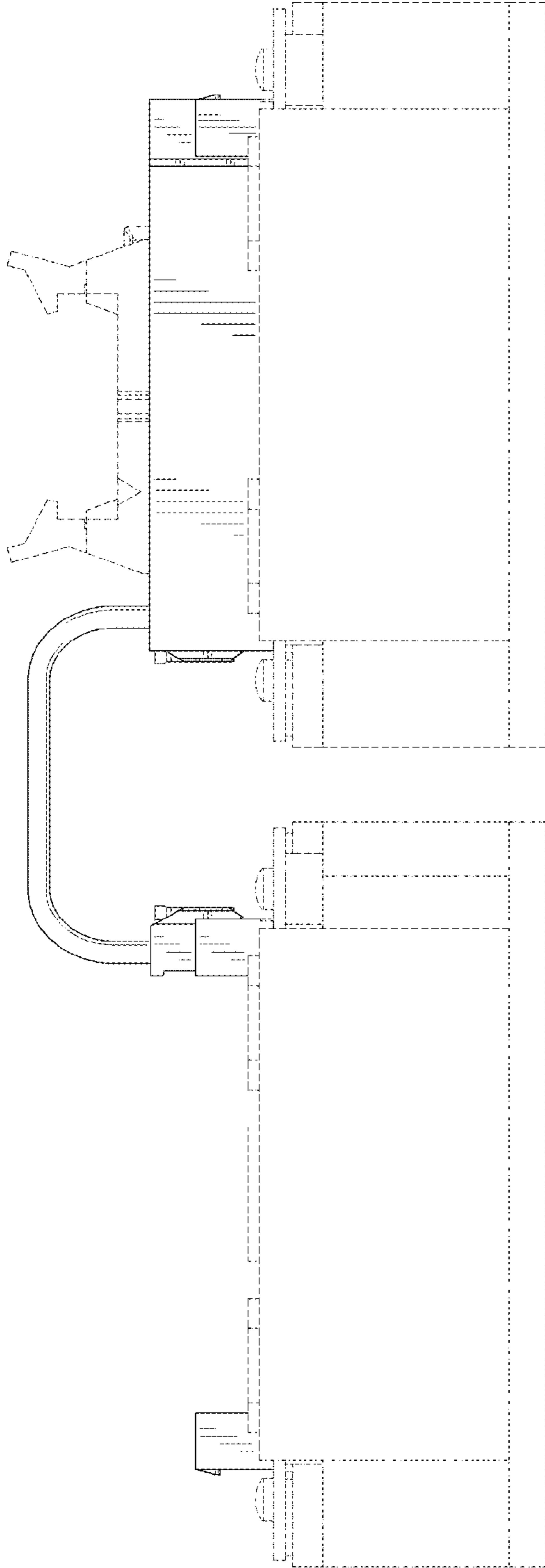


FIG. 2

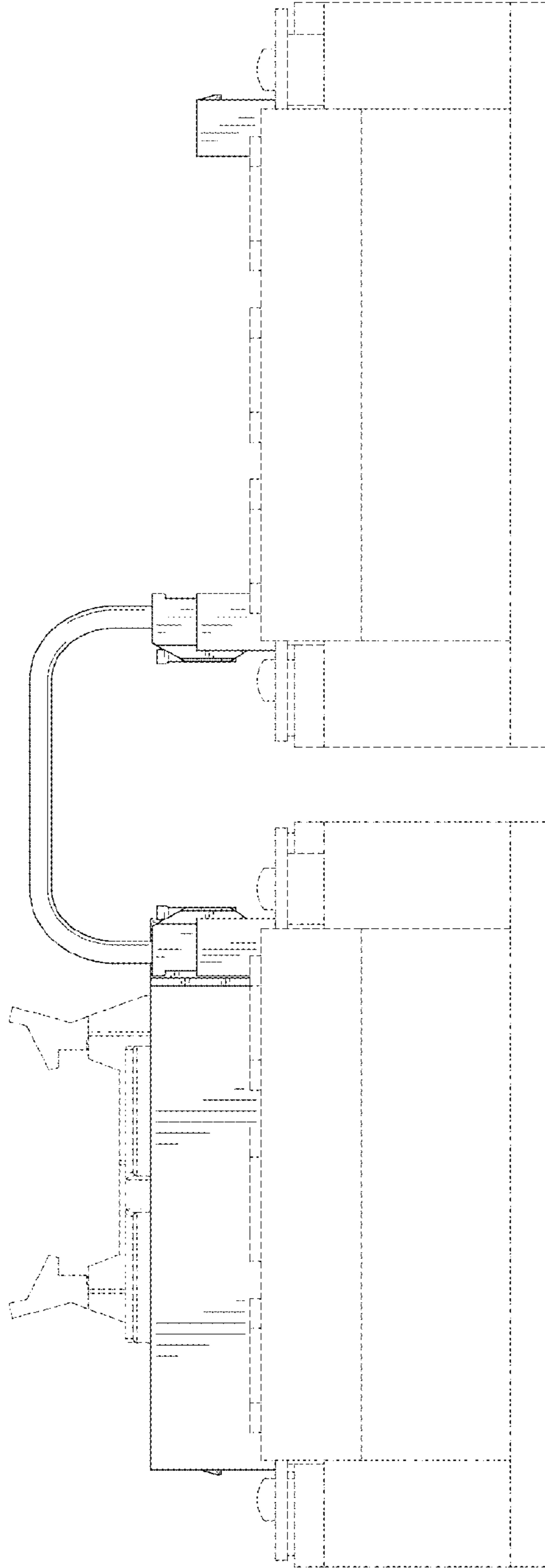


FIG. 3

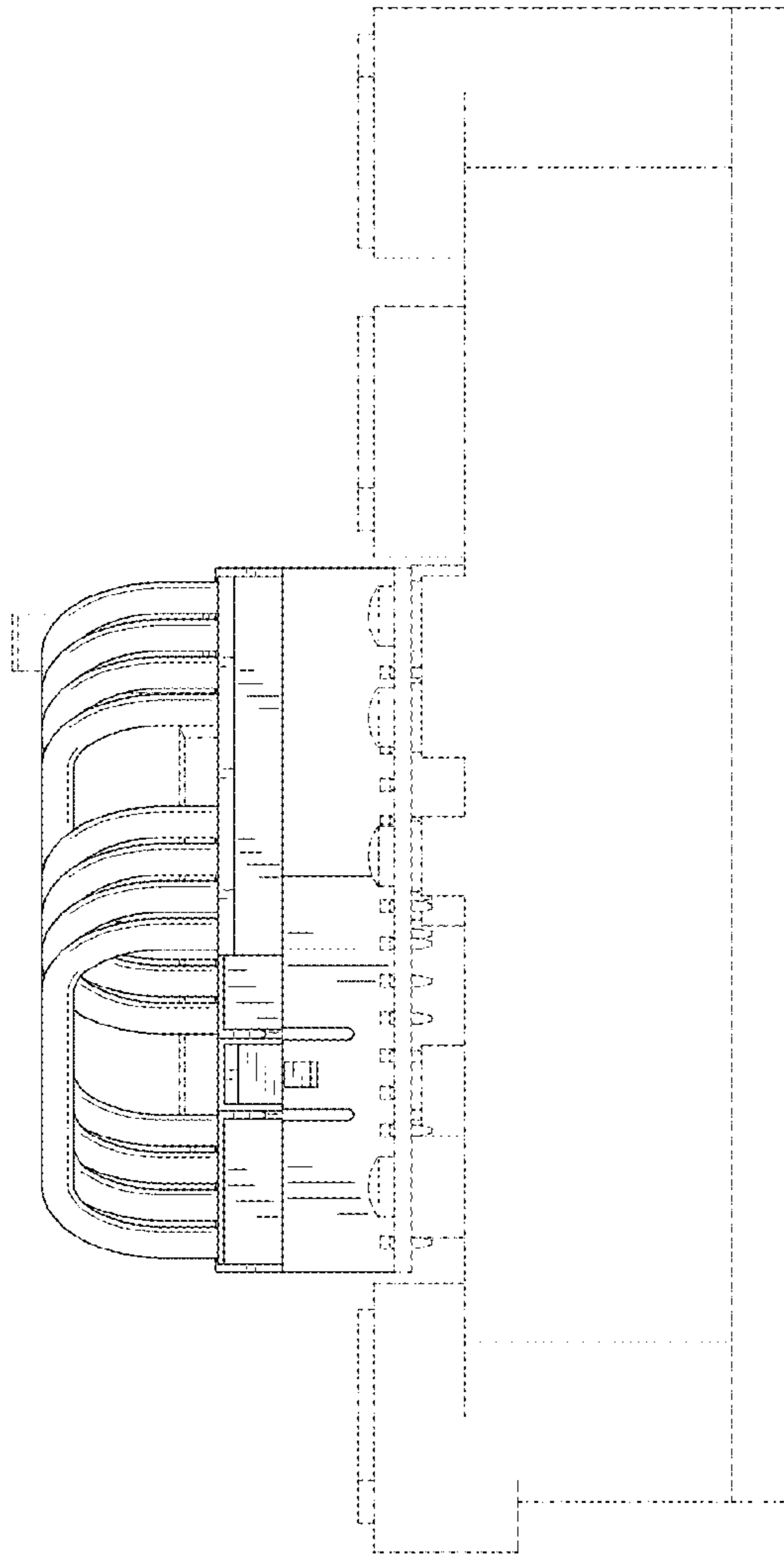


FIG. 4

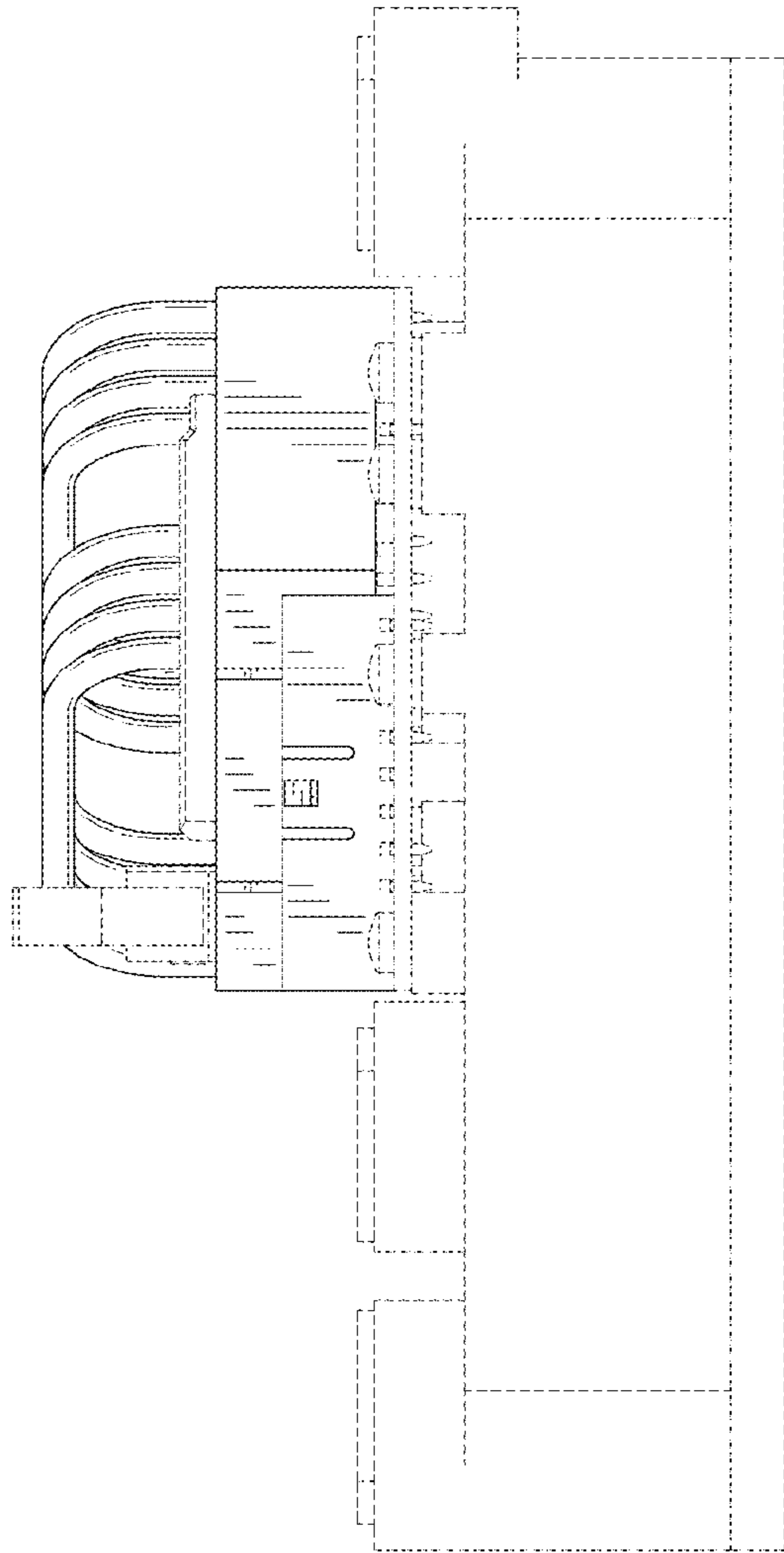


FIG. 5

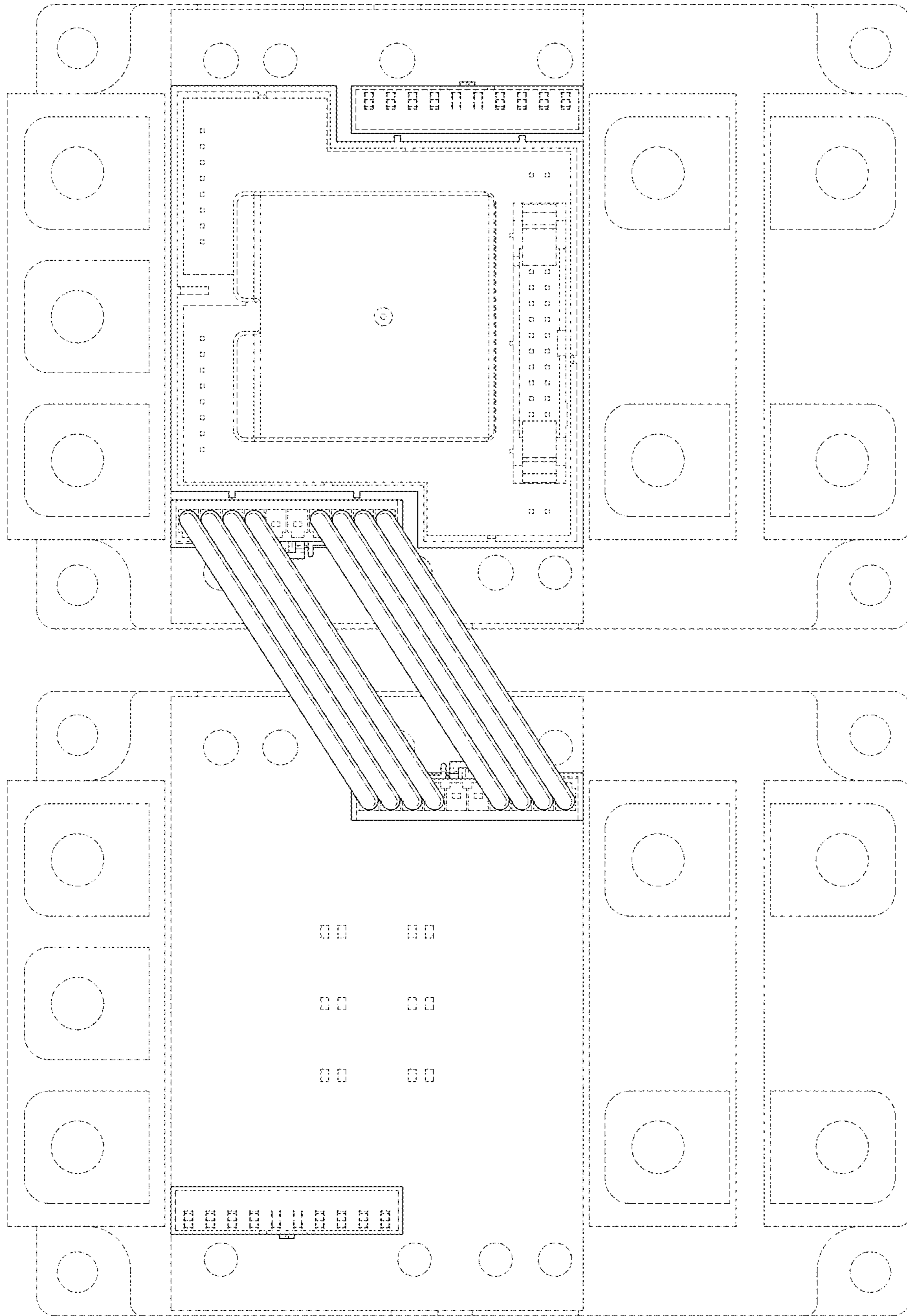


FIG. 6

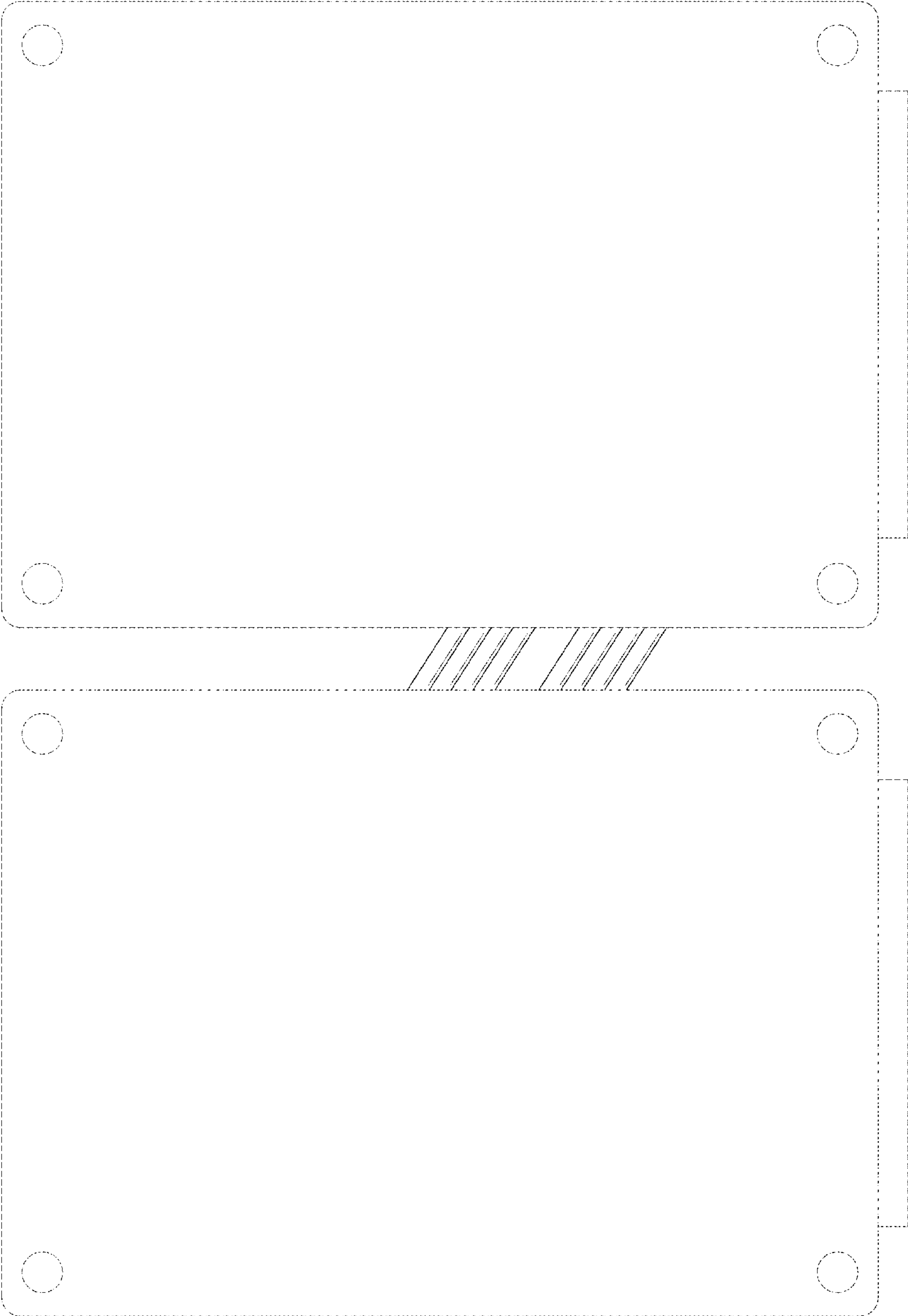


FIG. 7